ALPHA & OMEGA SEMICONDUCTOR

AOC2800

Common-Drain Dual N-Channel Enhancement Mode Field Effect Transistor

General Description

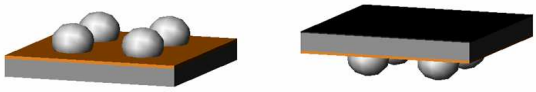
The AOC2800 uses advanced trench technology to provide excellent $R_{SS(ON)}$, low gate charge and operation with gate voltages as low as 2.5V while retaining a 12V $V_{GS(MAX)}$ rating. It is ESD protected. This device is suitable for use as a uni-directional or bi-directional load switch, facilitated by its common-drain configuration.

Product Summary

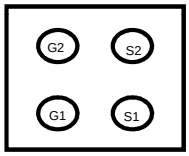
Vss	30V
I_D (at V_{GS}=4.5V)	6A
$R_{SS(ON)}$ (at V_{GS}=4.5V)	< 42mΩ
$R_{SS(ON)}$ (at V_{GS}=4.0V)	< 44mΩ
$R_{SS(ON)}$ (at V_{GS}=3.1V)	< 49mΩ
$R_{SS(ON)}$ (at V_{GS}=2.5V)	< 61mΩ

Green Product

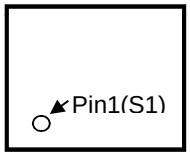
WLCSP 1.57x1.57_4



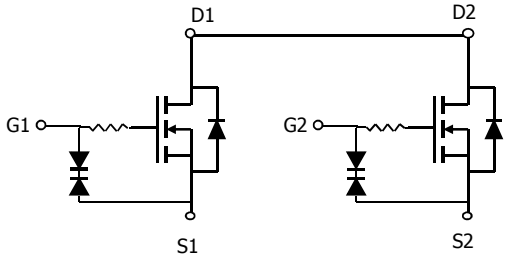
Bottom View



Top View



Equivalent Circuit



Absolute Maximum Ratings T_A=25°C unless otherwise noted

Parameter		Symbol	Maximum	Units
Source-Source Voltage		V_{SS}	**30**	V
Gate-Source Voltage		V_{GS}	**±12**	V
Source Current (DC) Note1	T_A=25°C	I_S	**6**	A
Source Current (Pulse) Note2		I_{SM}	**60**	
Power Dissipation Note1	T_A=25°C	P_D	**1.3**	W
Junction and Storage Temperature Range		T_J, T_{STG}	**-55 to 150**	°C

Note 1. Mounted on minimum pad PCB

Note 2. PW <300 µs pulses, duty cycle 0.5% max

Electrical Characteristics (T_J=25°C unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
STATIC PARAMETERS						
BV_{SSS}	Source-Source Breakdown Voltage	I_S=250µA, V_{GS}=0V, Test Circuit 6	30			V
I_{SSS}	Zero Gate Voltage Source Current	V_{SS}=20V, V_{GS}=0V, Test Circuit 1			1	µA
		T_J=55°C			5	
I_{GSS}	Gate leakage current	V_{SS}=0V, V_{GS}= ±10V, Test Circuit 2		1	10	
BV_{GSO}	Gate-Source Breakdown Voltage	V_{SS}=0V, I_G=±250µA, Test Circuit 7	±12			V
$V_{GS(th)}$	Gate Threshold Voltage	V_{SS}=V_{GS} I_S=250µA, Test Circuit 3	0.5	1	1.5	V
$R_{SS(ON)}$	Static Source to Source On-Resistance [Note]	V_{GS}=4.5V, I_S=3A, Test Circuit 4		35	42	mΩ
		T_J=125°C		53	63	
		V_{GS}=4.0V, I_S=3A, Test Circuit 4		37	44	
		V_{GS}=3.1V, I_S=3A, Test Circuit 4		41	49	
		V_{GS}=2.5V, I_S=3A, Test Circuit 4		49	61	
g_{FS}	Forward Transconductance [Note]	V_{SS}=5V, I_S=3A, Test Circuit 3		21		S
V_{FSS}	Diode Forward Voltage [Note]	I_S=1A,V_{GS}=0V, Test Circuit 5		0.7	1	V
DYNAMIC PARAMETERS						
C_{iss}	Input Capacitance	V_{GS}=0V, V_{SS}=15V, f=1MHz,		984	1180	pF
C_{oss}	Output Capacitance			93		pF
C_{rss}	Reverse Transfer Capacitance			57		pF
R_g	Gate resistance	V_{GS}=0V, V_{SS}=0V, f=1MHz		1.5		kΩ
SWITCHING PARAMETERS						
$t_{D(on)}$	Turn-On DelayTime	V_{GS}=10V, V_{SS}=15V, R_L=2.4Ω, R_{GEN}=6Ω ,		320		ns
t_r	Turn-On Rise Time			800		ns
$t_{D(off)}$	Turn-Off DelayTime			3.8		µs
t_f	Turn-Off Fall Time			3.6		µs
Q_g	Total Gate Charge	V_{G1S1}=4.5V, V_{SS}=15V, I_S=6A		9.1		nC

Note: Pulsed

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

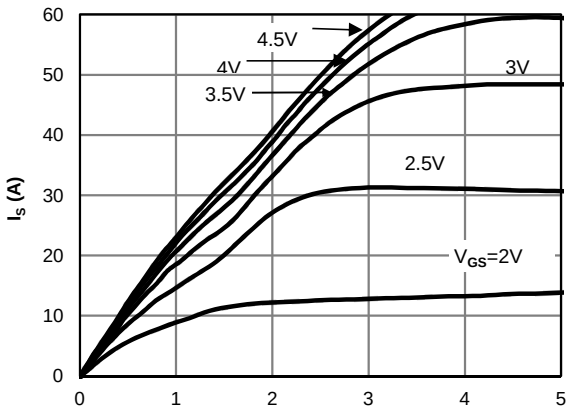
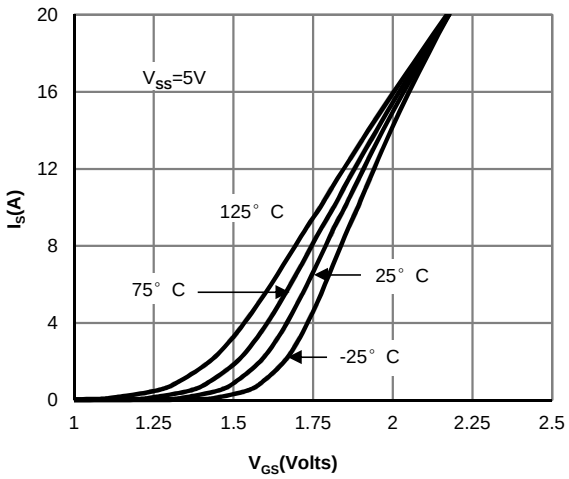


Fig 1: On-Region Characteristics



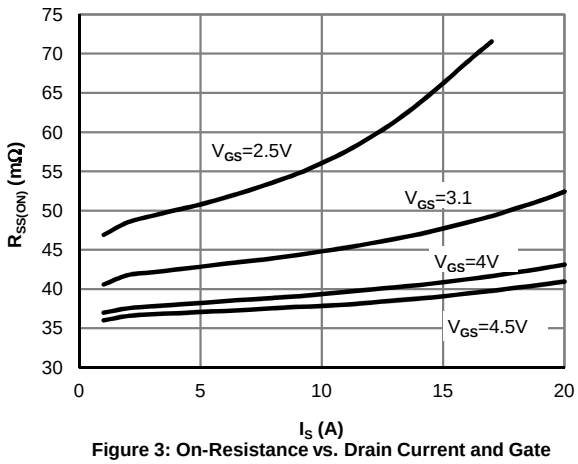


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

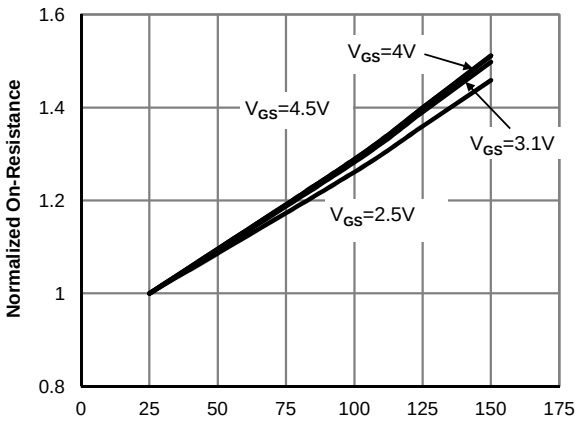


Figure 4: On-Resistance vs. Junction Temperature

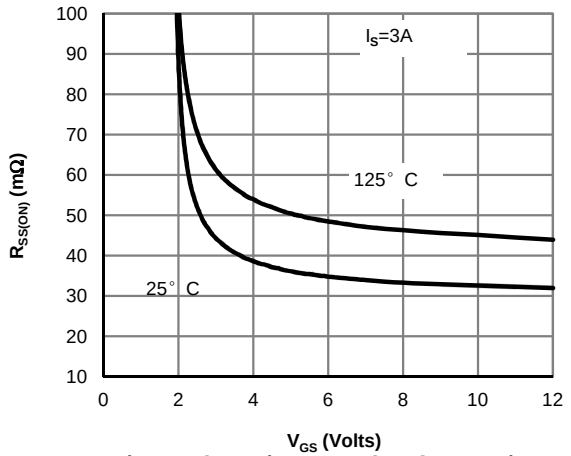


Figure 5: On-Resistance vs. Gate-Source Voltage

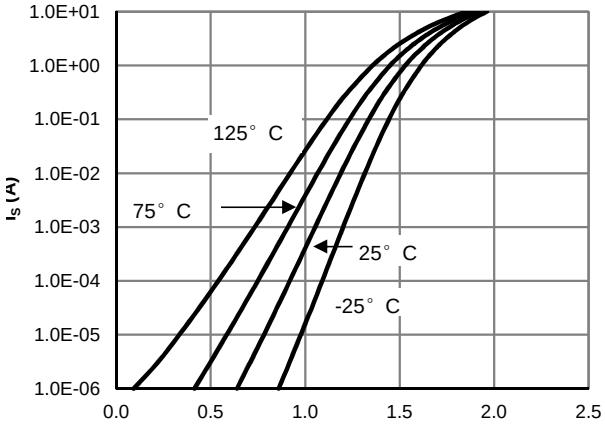


Figure 6: Body-Diode Characteristics

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

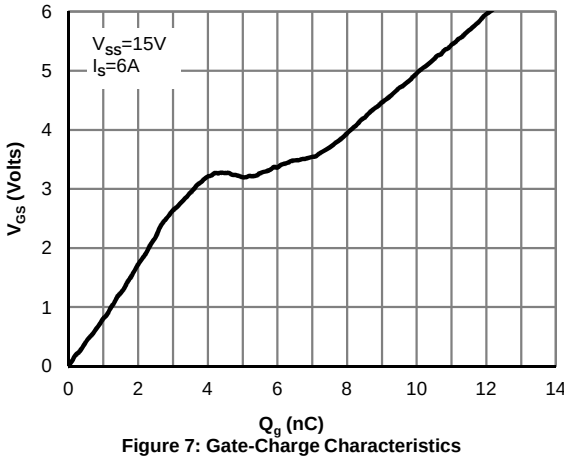


Figure 7: Gate-Charge Characteristics

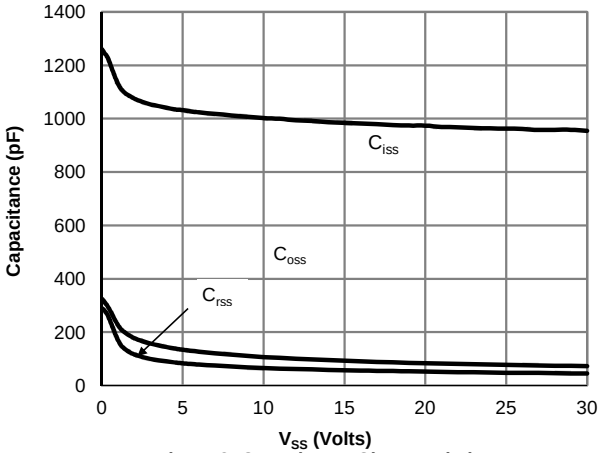


Figure 8: Capacitance Characteristics

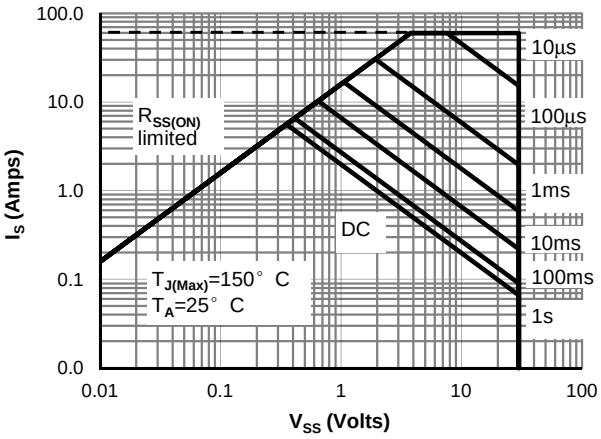


Figure 9: Maximum Forward Biased Safe Operating Area (Note E)

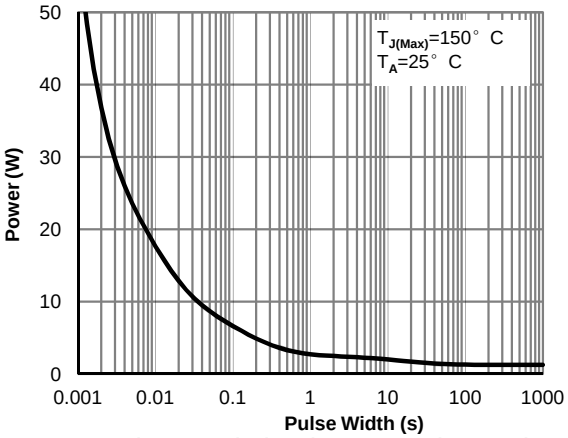


Figure 10: Single Pulse Power Rating Junction-to-Ambient (Note E)

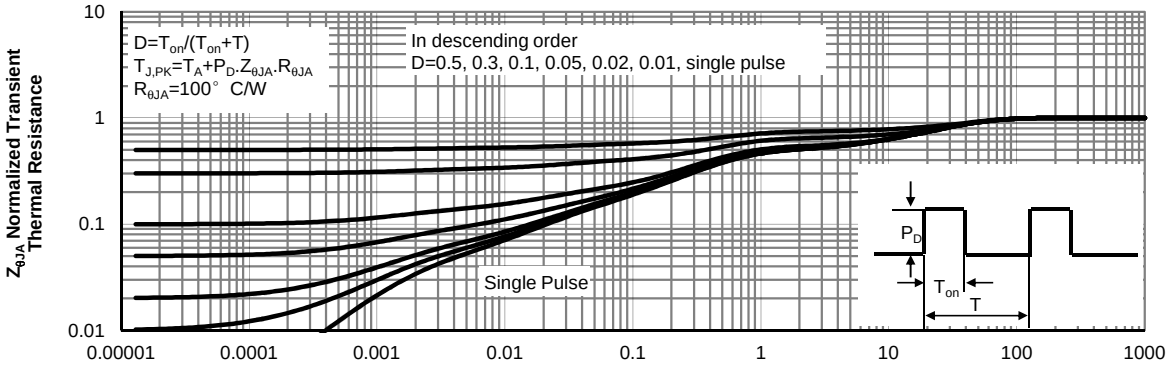
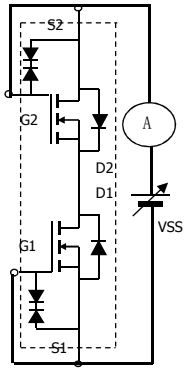


Figure 11: Normalized Maximum Transient Thermal Impedance

TEST CIRCUIT 1 Isss

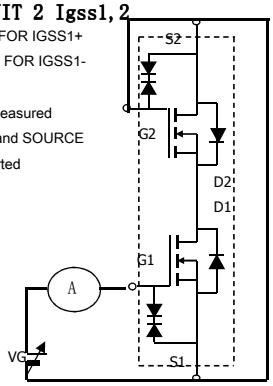
POSITIVE VSS FOR ISSS+
NEGATIVE VSS FOR ISSS-



TEST CIRCUIT 2 Igss1, 2

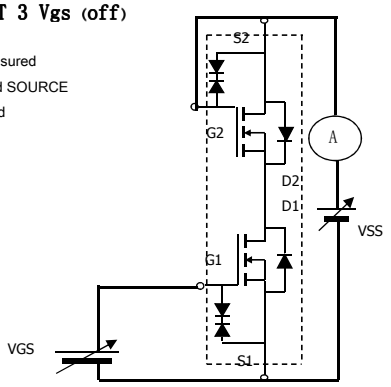
POSITIVE VGS FOR IGSS1+
NEGATIVE VGS FOR IGSS1-

When FET1 is measured
between GATE and SOURCE
of FET2 are shorted



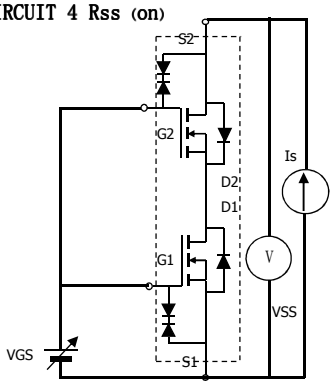
TEST CIRCUIT 3 Vgs (off)

When FET1 is measured
between GATE and SOURCE
of FET2 are shorted



TEST CIRCUIT 4 Rss (on)

Vss/Is

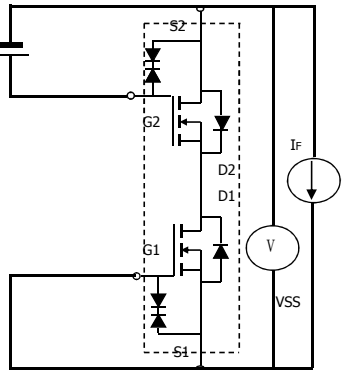


TEST CIRCUIT 5 $V_{F(SS)1,2}$

4.5V

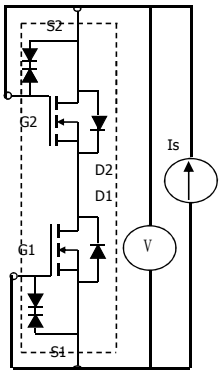
When FET1 measured
FET2 VGS=4.5V

VGS=0



TEST CIRCUIT 6 BV_{DSS}

POSITIVE VSS FOR ISSS+
NEGATIVE VSS FOR ISSS-



TEST CIRCUIT 7 $BV_{GS01,2}$

POSITIVE VSS FOR ISSS+
NEGATIVE VSS FOR ISSS-

When FET1 is measured
between GATE and SOURCE
of FET2 are shorted